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Publications

PUBLICATIONS

- **Spiral NeuroString: High-Density Soft Bioelectronic Fibers for Multimodal Sensing and Stimulation.** *bioRxiv : the preprint server for biology*
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- **Direct-print three-dimensional electrodes for large- scale, high-density, and customizable neural inter- faces.** *bioRxiv : the preprint server for biology*
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- **Ag-Diamond Core-Shell Nanostructures Incorporated with Silicon-Vacancy Centers.** *ACS materials Au*
Li, S., Francaviglia, L., Kohler, D. D., Jones, Z. R., Zhao, E. T., Ogletree, D. F., Weber-Bargioni, A., Melosh, N. A., Hamers, R. J.
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- **Etching- and intermediate-free graphene dry transfer onto polymeric thin films with high piezoresistive gauge factors** *JOURNAL OF MATERIALS CHEMISTRY C*
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